BAT54HT1G, NSVBAT54HT1G

Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 V (Typ) @ $I_F = 10 \text{ mAdc}$
- Device Marking: JV
- AEC Qualified and PPAP Capable
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS (T_J = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1)	PD		
$T_A = 25^{\circ}C$ Derate above 25°C		200 1.57	mW mW/°C
Forward Current (DC)	١ _F	200 Max	mA
Non-Repetitive Peak Forward Current, t _p < 10 msec	I _{FSM}	600	mA
Repetitive Peak Forward Current Pulse Wave = 1 sec, Duty Cycle = 66%	I _{FRM}	300	mA
Thermal Resistance Junction-to-Ambient	R_{\thetaJA}	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to150	°C

1. FR-4 Minimum Pad

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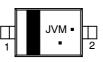
30 VOLT SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES



CASE 477 STYLE 1



MARKING DIAGRAM





(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
BAT54HT1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
NSVBAT54HT1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

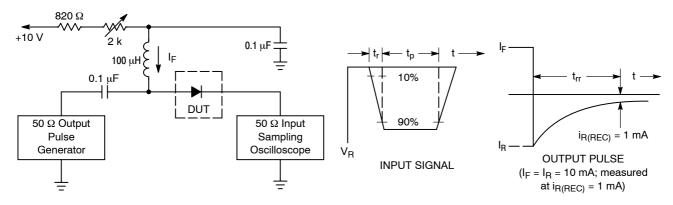
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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BAT54HT1G, NSVBAT54HT1G

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V _{(BR)R}	30	_	_	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	C _T	-	7.6	10	pF
Reverse Leakage (V _R = 25 V)	I _R	_	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mAdc)	V _F	_	0.22	0.24	Vdc
Forward Voltage (I _F = 30 mAdc)	V _F	_	0.41	0.5	Vdc
Forward Voltage (I _F = 100 mAdc)	V _F	_	0.52	0.8	Vdc
Reverse Recovery Time ($I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}$) Figure 1	t _{rr}	_	_	5.0	ns
Forward Voltage (I _F = 1.0 mAdc)	V _F	_	0.29	0.32	Vdc
Forward Voltage (I _F = 10 mAdc)	V _F	_	0.35	0.40	Vdc

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)



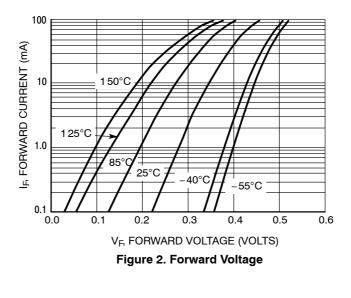
Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA. 2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA.

3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

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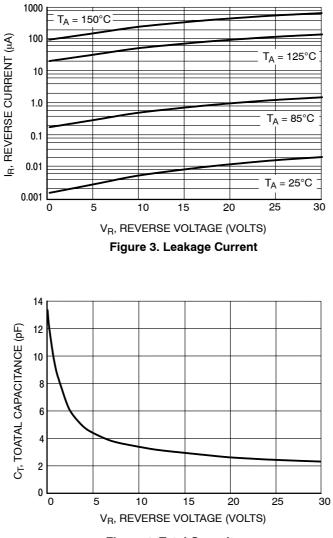


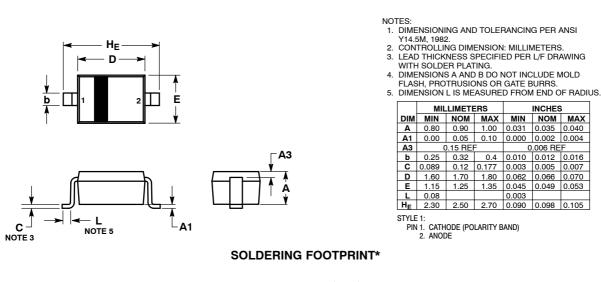
Figure 4. Total Capacitance

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BAT54HT1G, NSVBAT54HT1G

PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE H



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0.025 \\
\hline
0.025 \\
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0.033 \\$

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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